

**SLOVENSKI STANDARD  
SIST EN IEC 60749-21:2026****01-marec-2026****Nadomešča:  
SIST EN 60749-21:2011**

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**Polprevodniški elementi - Metode za mehansko in klimatsko preskušanje - 21. del:  
Spajkljivost (IEC 60749-21:2025)**Semiconductor devices - Mechanical and climatic test methods - Part 21: Solderability  
(IEC 60749-21:2025)Halbleiterbauelemente - Mechanische und klimatische Prüfverfahren - Teil 21: Lötbarkeit  
(IEC 60749-21:2025)Dispositifs à semiconducteurs - Méthodes d'essais mécaniques et climatiques - Partie  
21: Brasabilité (IEC 60749-21:2025)**Ta slovenski standard je istoveten z: EN IEC 60749-21:2026****ICS:**

19.020	Preskuševalni pogoji in postopki na splošno	Test conditions and procedures in general
31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general

**SIST EN IEC 60749-21:2026****en**

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EUROPEAN STANDARD  
NORME EUROPÉENNE  
EUROPÄISCHE NORM

**EN IEC 60749-21**

January 2026

ICS 31.080.01

Supersedes EN 60749-21:2011

English Version

**Semiconductor devices - Mechanical and climatic test methods -  
Part 21: Solderability  
(IEC 60749-21:2025)**

Dispositifs à semiconducteurs - Méthodes d'essais  
mécaniques et climatiques - Partie 21: Brasabilité  
(IEC 60749-21:2025)

Halbleiterbauelemente - Mechanische und klimatische  
Prüfverfahren - Teil 21: Lötbarkeit  
(IEC 60749-21:2025)

This European Standard was approved by CENELEC on 2026-01-13. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

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European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels**

## EN IEC 60749-21:2026 (E)

### European foreword

The text of document 47/2961/FDIS, future edition 3 of IEC 60749-21, prepared by TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 60749-21:2026.

The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2027-01-31 level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the (dow) 2029-01-31 document have to be withdrawn

This document supersedes EN 60749-21:2011 and all of its amendments and corrigenda (if any).

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### Endorsement notice

The text of the International Standard IEC 60749-21:2025 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standard indicated:

IEC 60068-2-69	NOTE	Approved as EN 60068-2-69
IEC 60749-15	NOTE	Approved as EN IEC 60749-15
IEC 60749-20	NOTE	Approved as EN IEC 60749-20

## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cencenelec.eu](http://www.cencenelec.eu).

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61190-1-2	2014	Attachment materials for electronic assembly - Part 1-2: Requirements for soldering pastes for high-quality interconnects in electronics assembly	EN 61190-1-2	2014
IEC 61190-1-3	2017	Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solder for electronic soldering applications	EN IEC 61190-1-3	2018

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# INTERNATIONAL STANDARD

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**Semiconductor devices - Mechanical and climatic test methods -  
Part 21: Solderability**

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